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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Keep safety first in your circuit designs!

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HSM2694

Silicon Epitaxial Planar Diode for Tuner Band Switch



ADE-208-095A (Z)

Rev. 1
Jun. 1993

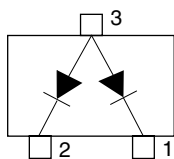
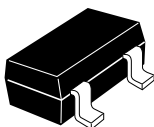
Features

- Low forward resistance. ($r_f = 0.9\Omega_{\text{max}}$)
- Low capacitance. ($C = 1.2\text{pF}_{\text{max}}$)
- MPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HSM2694	B3	MPAK

Pin Arrangement



(Top View)

- 1 Cathode
- 2 Cathode
- 3 Anode

Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V_R	35	V
Power dissipation	P_d^*	150	mW
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	-45 to +125	°C
Operation temperature	T_{opr}	-20 to +60	°C

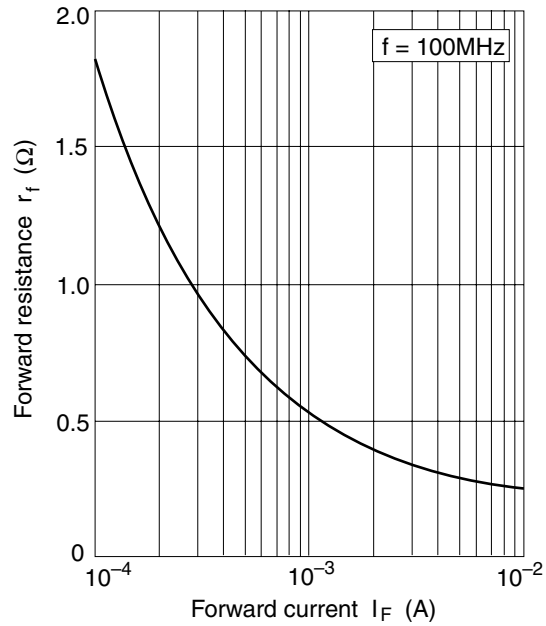
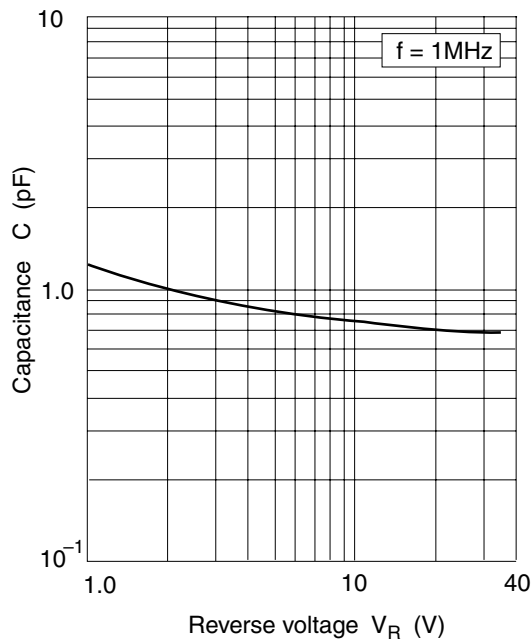
Note: Two device total

Electrical Characteristics *

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse voltage	V_R	35	—	—	V	$I_R = 10\mu A$
Reverse current	I_R	—	—	50	nA	$V_R = 25V$
Forward voltage	V_F	—	—	1.0	V	$I_F = 10mA$
Capacitance	C	—	—	1.2	pF	$V_R = 6V, f = 1MHz$
Forward resistance	r_f	—	—	0.9	Ω	$I_F = 2mA, f = 100MHz$

Note: Per one device

**Fig.1 Forward resistance Vs. Forward current****Fig.2 Capacitance Vs. Reverse voltage**

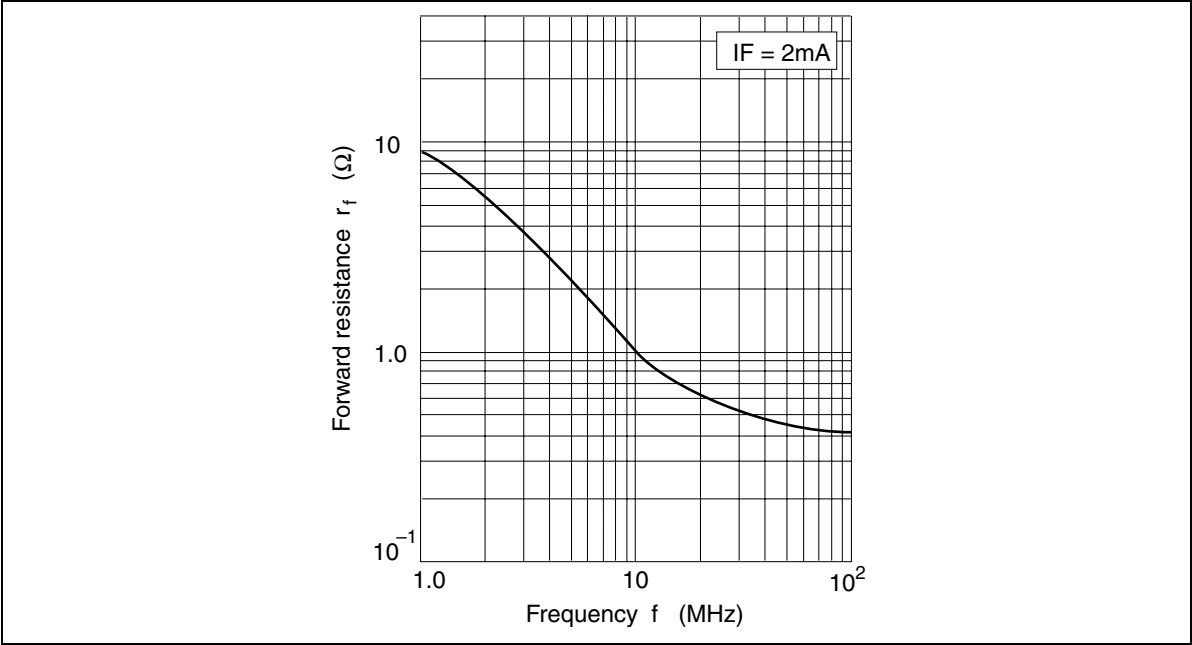
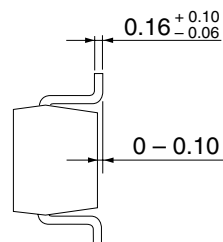
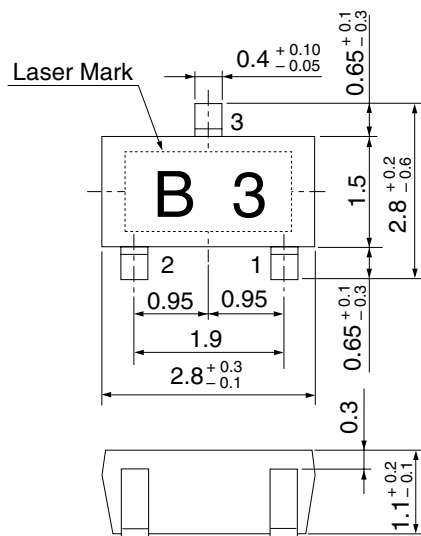


Fig.3 Forward resistance Vs. Frequency

Package Dimensions

Unit: mm



- 1 Cathode
- 2 Cathode
- 3 Anode

HITACHI Code	MPAK(1)
JEDEC Code	—
EIAJ Code	SC-59A
Weight (g)	0.011

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